



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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PRODUCT NUMBER
89883-YXXXXLF

- ROHS COMPATIBLE, SEE NOTE 5.
- OPTIONAL LETTER
- H: HIGH TEMPERATURE PRODUCT.
- NUMBER OF POSITIONS PER ROW: 02 TO 65.
- PLATING CODE
- 3= 0.76µm GOLD ON CONTACT AREA.
- 2µm MIN MATTE TIN ON TAIL.
- 4= 2µm MIN MATTE TIN FULL PLATED
- 1.27µm Ni MIN UNDERPLATING

NOTES:

- 1 - HOUSING MAT'L: THERMOPLASTIC GLASS FILLED FLAME RETARDANT PER UL 94 V-0.
LOW TEMPERATURE: COLOR BLUE.
HIGH TEMPERATURE: COLOR GREY.
- 2 - TERMINAL MATERIAL: PHOSPHOR BRONZE.
- 3 - 2 UP TO 4 POSITIONS PRODUCT PACKED IN PLASTIC BOX.
- 5 UP TO 65 POSITIONS PRODUCT PACKED IN TUBE.
- 4 - TO DETERMINE DIMENSIONS:
N = NUMBER OF POSITIONS PER ROW
EXAMPLE: 8 POS: (Nx2.54)-0.08=20.24 mm.
- 5 - ROHS COMPATIBLE PRODUCT SPECIFICATIONS

d - PLATING:

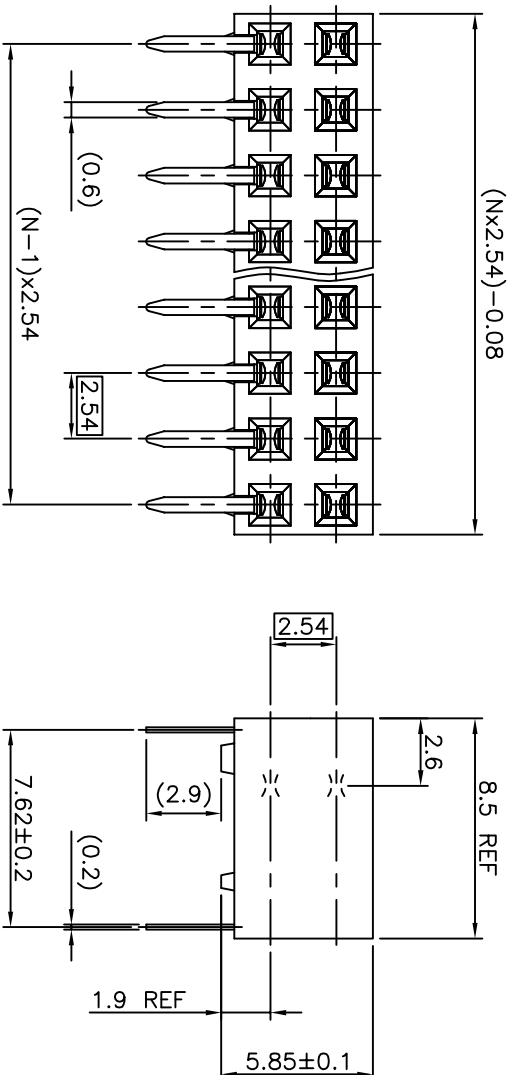
- "LF" MEANS THE PRODUCT IS LEAD-FREE, 2µm MINIMUM MATTE TIN OVER 1.27µm MINIMUM NICKEL UNDERPLATE.

b - MANUFACTURING PROCESS COMPATIBILITY

- THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C ±5°C SOLDER BATH TEMPERATURE FOR 5 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.6mm MIN THICK CIRCUIT BOARD.

c - LABELING:

- MEETS PACKAGING SPECS AS PER GS-14-920
- LEGAL STATEMENT: SEE GS-47-0004



mat'l. code	SEE NOTES	surface	tolerance	projection	product family
tr	ecn no dr date	ISO 1302	ISO 406 ISO 1101	ISO 1101	DUBOX
C	F60362 PNZ 96.05.20	tolerances unless otherwise specified	±0.3		
D	F60461 PNZ 96.06.20	linear			
E	F70454 PNZ 97.06.23	±2°		mm	
F	F10110 GC0 01.01.16 dr	D LEGRAND	04.09.28	scale 5:1	
G	F04-0347 DLE 04.09.28 engf	P NIZZI	04.09.28		
H	F06-0204 DLE 06.06.21 chr	D LEGRAND	04.09.28		
J	B-19123 LMU 14.10.21 qppd	P NZ	04.09.28		
sheet	revision	J	B		
index	sheet	1	2		

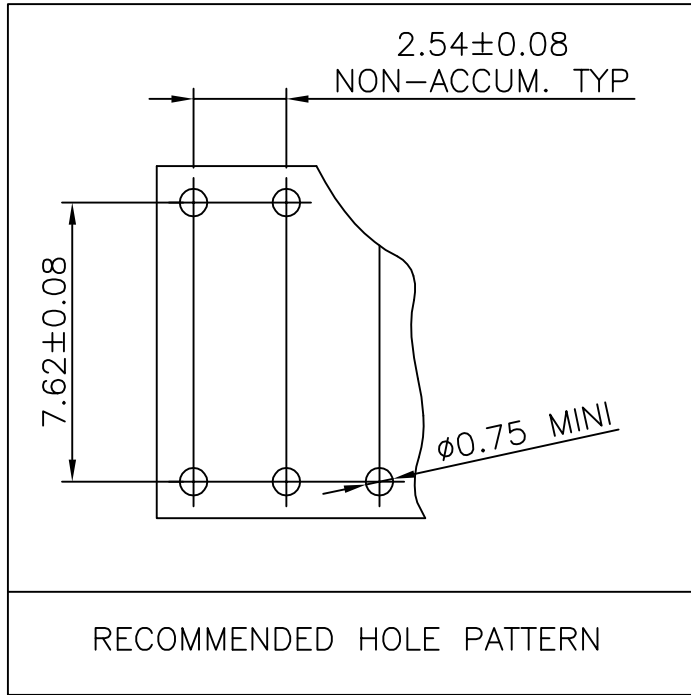
title
BtB RECEIPT.
HORIZ DR TMT

dwg no
89883

sheet 1 of 2
A3

type
CUSTOMER

Drawing



FCIconnect.com

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mat'l. code SEE SHEET 1				surface ISO 1302 <input checked="" type="checkbox"/>		tolerance ISO 406 ISO 1101		projection 		product family DUBOX				
ltr	ecn no	dr	date	tolerances unless otherwise specified				mm 		title BtB RECEPT. HORIZ DR TMT				
A	F04-0347	DLE	04.09.28	angles linear	±0.3				scale 5:1		dwg no 89883		sheet 2 of 2 size A4	
B	F06-0204	DLE	06.06.21		±2'									
				dr	D LEGRAND	04.09.28				type CUSTOMER Drawing				
				enr	P NIZZI	04.09.28								
				chr	D LE	04.09.28								
				appd	P NZ	04.09.28								
sheet index	revision sheet													